

# Using the CSD86330EVM-717

## User's Guide



Literature Number: SLUU480  
February 2011

# ***Synchronous Buck NexFET Power Block***

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## **1 Introduction**

The CSD86330EVM-717 evaluation module (EVM) uses the CSD86330. The CSD86330 power block is an optimized design for synchronous buck applications offering high-current, high-efficiency, and high-frequency capability in a small 3.3-mm x 3.3-mm outline. CSD86330EVM-717 also uses TPS53219 as a small size single-buck controller with adaptive on-time D-CAP™ mode control. The EVM provides a fixed 1.2-V output at up to 10 A from a 12-V input bus.

## **2 Description**

The CSD86330EVM-717 is designed to use a regulated 12-V bus to produce a regulated 1.2-V output at up to 10 A of load current. The CSD86330EVM-717 is designed to demonstrate the CSD86330 device in a typical low-voltage application while providing test points to evaluate the performance of the board.

### **2.1 Typical Applications**

- Point-of-Load Systems
- Storage Computer
- Server Computer
- Multi-Function Printer
- Embedded Computing

### **2.2 Features**

The CSD86330EVM-717 features:

- 10-A DC Steady State Output Current
- High Efficiency and High-Power Density by Using TI Power Block MOSFET (CSD86330)
- Convenient Test Points for Probing Critical Waveforms

### 3 Electrical Performance Specifications

**Table 1. CSD86330EVM-717 Electrical Performance Specifications**

| PARAMETER                       | TEST CONDITIONS   | MIN   | TYP | MAX   | UNITS            |
|---------------------------------|---|-------|-----|-------|------------------|
| <b>Input Characteristics</b>    |   |       |     |       |                  |
| Voltage range                   | V <sub>IN</sub>   | 9     | 12  | 13.2  | V                |
| Maximum input current           | V <sub>IN</sub> = 9 V, I <sub>O</sub> = 10 A                              |       | 1.6 |       | A                |
| No load input current           | V <sub>IN</sub> = 13.2 V, I <sub>O</sub> = 0 A                            |       | 1   |       | mA               |
| <b>Output Characteristics</b>   |   |       |     |       |                  |
| Output voltage V <sub>OUT</sub> | I <sub>O</sub> = 5 A  | 1.164 | 1.2 | 1.236 | V                |
| Output voltage regulation       | Line regulation(V <sub>IN</sub> = 9 V 13.2 V, I <sub>O</sub> =0 A - 10 A) | 0.5%  |     |       |                  |
|                                 | Load regulation(V <sub>IN</sub> = 12 V, I <sub>O</sub> = 0 A - 10 A)      | 0.5%  |     |       |                  |
| Output voltage ripple           | V <sub>IN</sub> = 12 V, I <sub>O</sub> = 10 A                             | 40    |     |       | mV <sub>PP</sub> |
| Output load current             |   | 0     |     | 10    | A                |
| Output over current             |   | 12    |     |       |                  |
| <b>Systems Characteristics</b>  |   |       |     |       |                  |
| Switching frequency             |   | 500   |     |       | kHz              |
| Peak efficiency                 | V <sub>IN</sub> = 9 V, 1.2 V/5 A  | 92%   |     |       |                  |
| Full load efficiency            | V <sub>IN</sub> = 12 V, 1.2 V/10 A  | 89.4% |     |       |                  |
| Operating temperature           |   | 25    |     |       | °C               |



## 5 Test Setup

### 5.1 Test Equipment

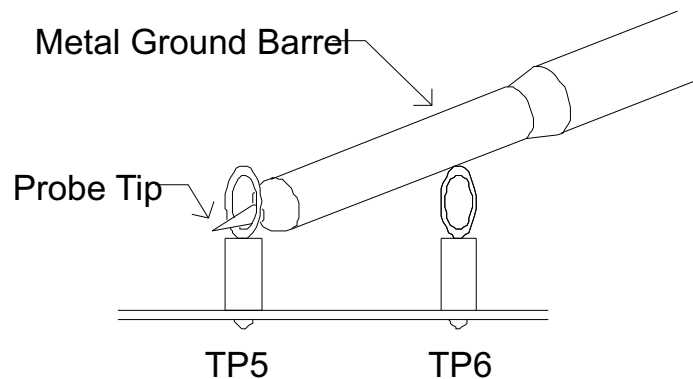
**Voltage Source:** The input voltage source  $V_{IN}$  should be a 0-V to 13.2-V variable DC source capable of supplying 4 A<sub>DC</sub>. Connect  $V_{IN}$  to board as shown in [Figure 3](#).

**Multimeters:**

- V1:  $V_{IN}$  at TP1 ( $V_{IN}$ ) and TP2 (GND).
- V2:  $V_{OUT}$  at TP5 ( $V_{OUT}$ ) and TP6 (GND).
- A1:  $V_{IN}$  input current.

**Output Load:** The output load should be an electronic constant resistance mode load capable of 0 A<sub>DC</sub> to 10 A<sub>DC</sub> at 1.2 V.

**Oscilloscope:** A digital or analog oscilloscope can be used to measure the output ripple. The oscilloscope should be set for 1-M $\Omega$  impedance, 20-MHz bandwidth, AC coupling, 1- $\mu$ s/division horizontal resolution, 50-mV/division vertical resolution. Test points TP5 and TP6 can be used to measure the output ripple voltage by placing the oscilloscope probe tip through TP5 and holding the ground barrel TP6 as shown in [Figure 2](#). Using a leaded ground connection may induce additional noise due to the large ground loop.



**Figure 2. Tip and Barrel Measurement for  $V_{OUT}$  Ripple**

**Fan:** Some of the components in this EVM may approach temperatures of 60°C during operation. A small fan capable of 200 LFM to 400 LFM is recommended to reduce component temperatures while the EVM is operating. The EVM should not be probed if the fan is not running.

**Recommended Wire Gauge:**

- **VIN to VIN1(12-V input):** The recommended wire size is 1x AWG #18 per input connection, with the total length of wire less than 4 feet (a 2 foot input and a 2 foot return).

**VOUT1 to LOAD:** The recommended wire size is 1x AWG #18, with the total length of wire less than 4 feet (a 2 foot input and a 2 foot return).

## 5.2 Recommended Test Setup

Figure 3 is the recommended test set up to evaluate the CSD86330EVM-717. Working at an ESD workstation, make sure that any wrist straps, bootstraps or mats are connected referencing the user to earth ground before power is applied to the EVM.

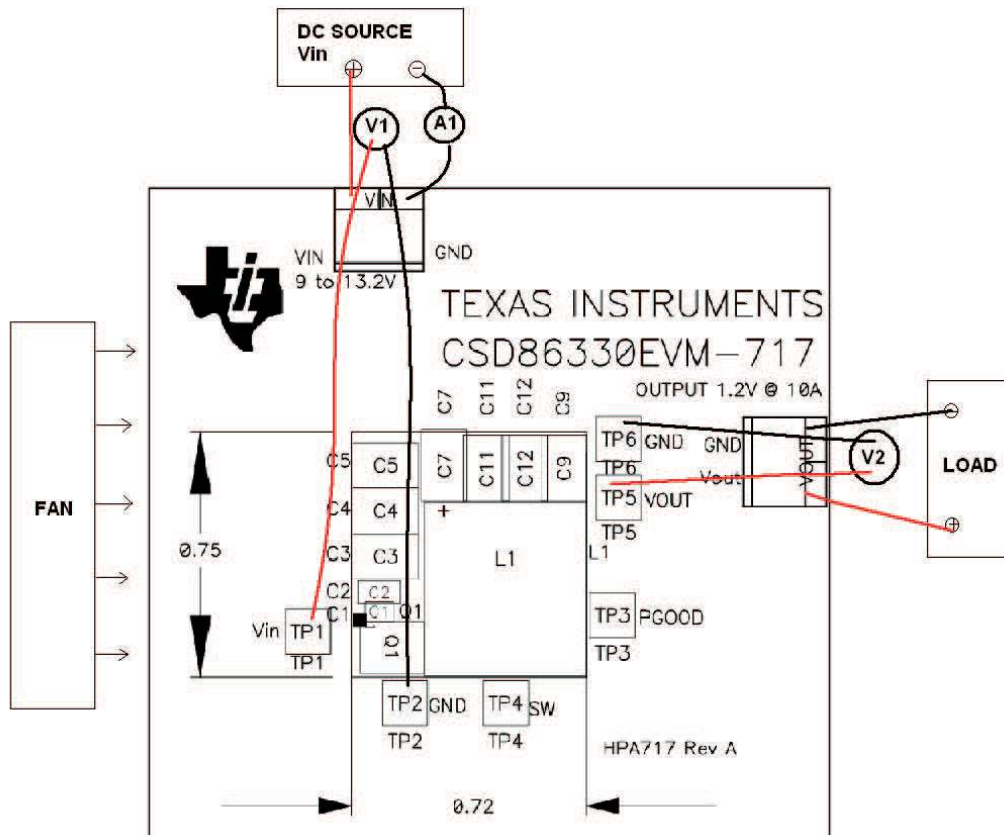


Figure 3. CSD86330EVM-717 Recommended Test Set Up

### Input Connections:

- Prior to connecting the DC input source  $V_{IN}$ , it is advisable to limit the source current from  $V_{IN}$  to 10 A maximum. Make sure  $V_{IN}$  is initially set to 0 V and connected as shown in Figure 3.
- Connect a voltmeter V1 at TP1( $V_{IN}$ ) and TP2(GND) to measure the input voltage.
- Connect a current meter A1 to measure the input current.

### Output Connections:

- Connect load to VOUT1 and set load to constant resistance mode to sink 0  $A_{DC}$  before  $V_{IN}$  is applied.
- Connect a voltmeter V2 at TP5 ( $V_{OUT}$ ) and TP6 (GND) to measure the output voltage.

**Other Connections:** Place a fan as shown in Figure 3 and turn on, making sure air is flowing across the EVM.

## 6 Test Procedure

### 6.1 Line/Load Regulation and Efficiency Measurement Procedure

1. Set up the EVM as described in [Section 5](#) and [Figure 3](#).
2. Ensure load is set to constant resistance mode and to sink 0 A<sub>DC</sub>.
3. Ensure all configuration settings are as per [Section 6](#).
4. Increase V<sub>IN</sub> from 0 V to 12 V. Using V1 to measure input voltage.
5. Use V2 to measure V<sub>OUT</sub> voltage.
6. Vary load from 0 A<sub>DC</sub> to 10 A<sub>DC</sub>, V<sub>OUT</sub> should remain in load regulation.
7. Vary V<sub>IN</sub> from 9 V to 13.2 V, V<sub>OUT</sub> should remain in line regulation.
8. Decrease load to 0 A.
9. Decrease V<sub>IN</sub> to 0 V.

### 6.2 List of Test Points

**Table 2. Test Point Functions**

| TEST POINTS | NAME             | DESCRIPTION                             |
|-------------|------------------|---|
| TP1         | V <sub>IN</sub>  | Input voltage measurement point         |
| TP2         | GND              | Ground for V <sub>IN</sub> measurements |
| TP3         | PGOOD            | Power Good monitoring point             |
| TP4         | SW               | Switch Node monitoring point            |
| TP5         | V <sub>OUT</sub> | Output Voltage measurement point        |
| TP6         | GND              | Ground for output voltage measurements  |

### 6.3 Equipment Shutdown

1. Shut down load
2. Shut down V<sub>IN</sub>
3. Shut down fan

## 7 Performance Data and Typical Characteristic Curves

Figure 4 through Figure 11 present typical performance curves for CSD86330EVM-717.

### 7.1 Efficiency

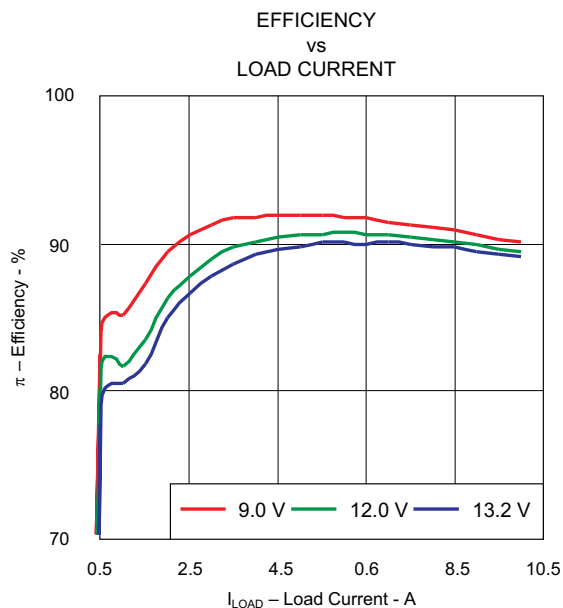


Figure 4. Efficiency

### 7.2 Light-Load Efficiency

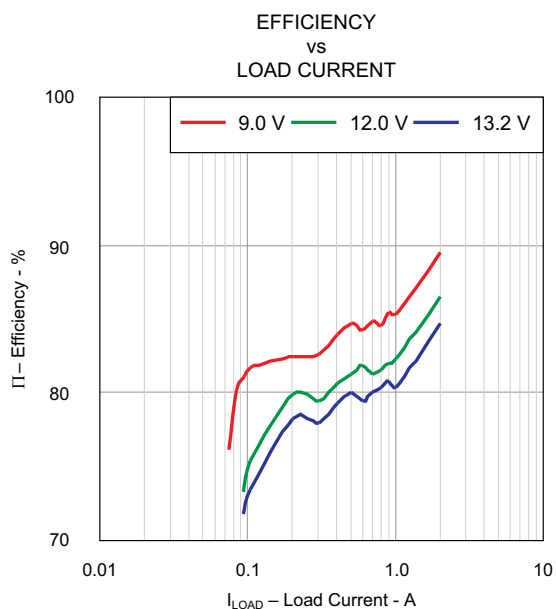


Figure 5. Light-Load Efficiency



### 7.3 Load Regulation

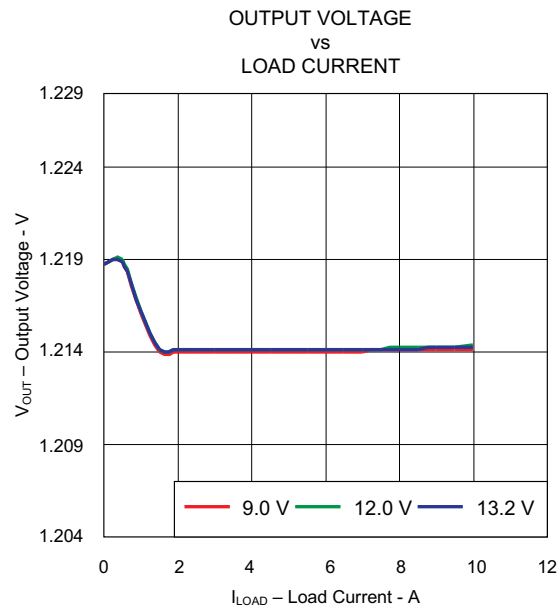


Figure 6. Load Regulation

### 7.4 Output Transient

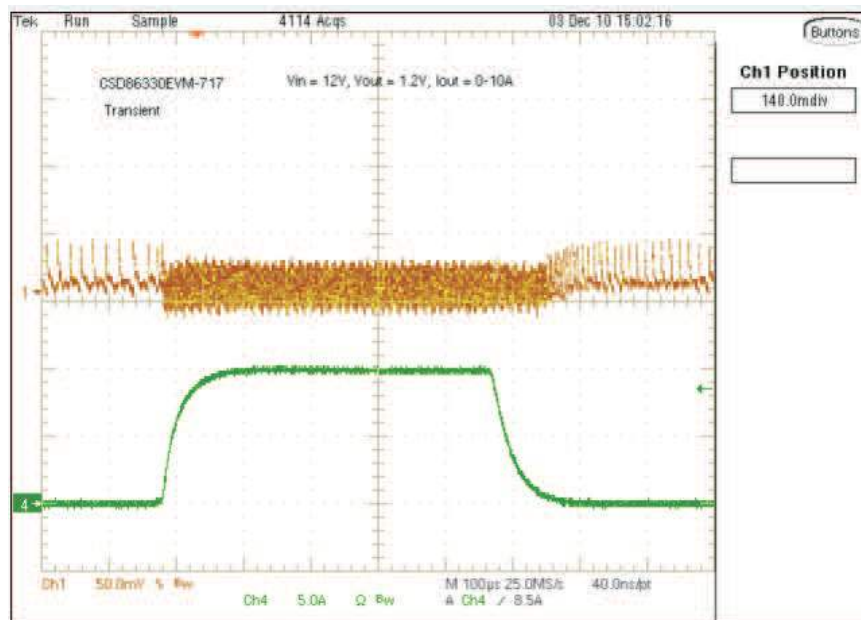


Figure 7. Output-Load Transient

## 7.5 Output Ripple

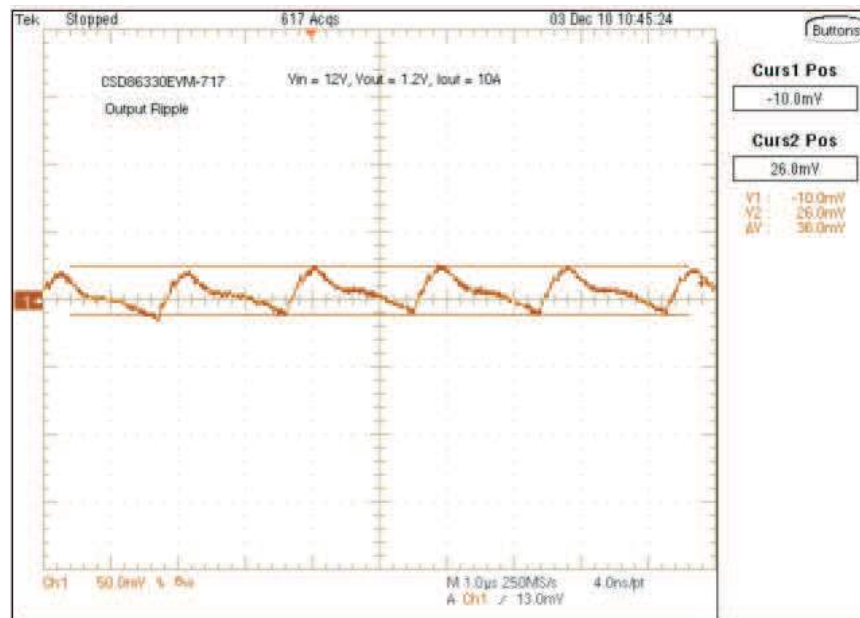


Figure 8. Output Ripple

## 7.6 Switching Node

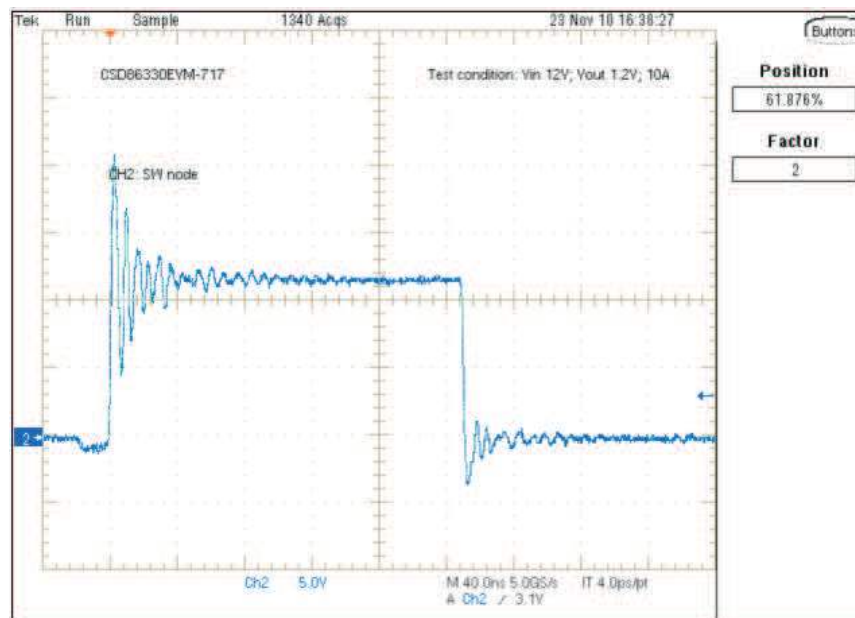


Figure 9. Output Ripple

## 7.7 Thermal Image

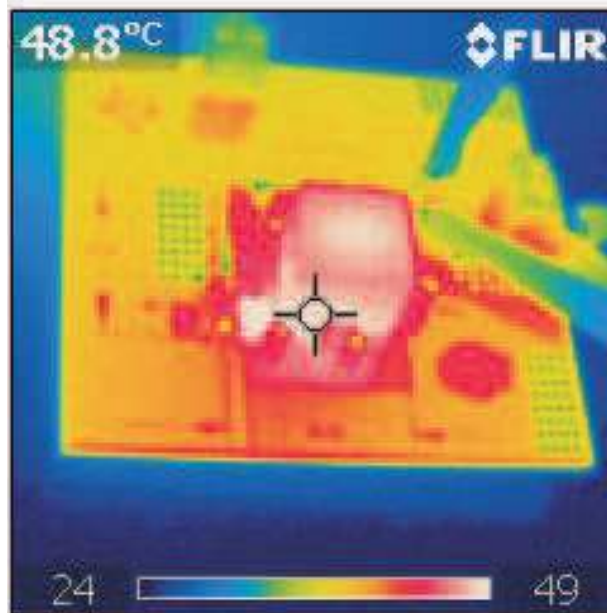


Figure 10. Top Board at 12 V<sub>IN</sub>, 1.2 V/10 A with natural air convection

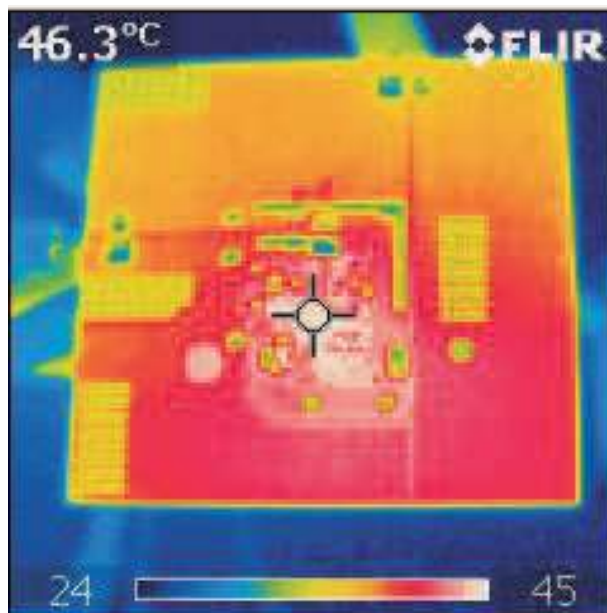


Figure 11. Bottom Board at 12 V<sub>IN</sub>, 1.2 V/10 A with natural air convection

### 8 CSD86330EVM-717 Assembly Drawing and PCB Layout

The following figures (Figure 12 through Figure 19) show the design of the CSD86330EVM-717 printed circuit board. The EVM has been designed using six layers and a 2-oz copper circuit board.

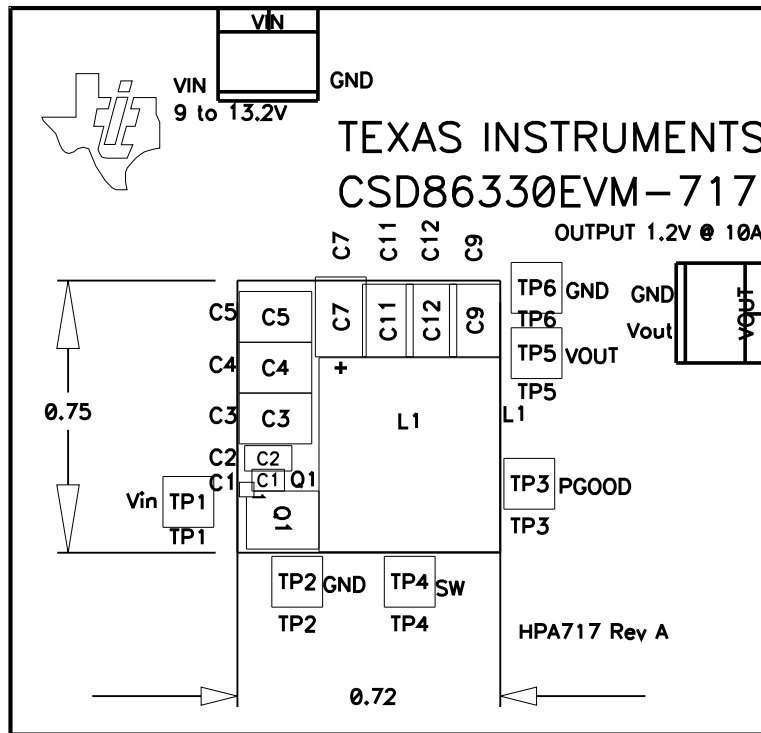


Figure 12. Top Layer Assembly Drawing (top view)

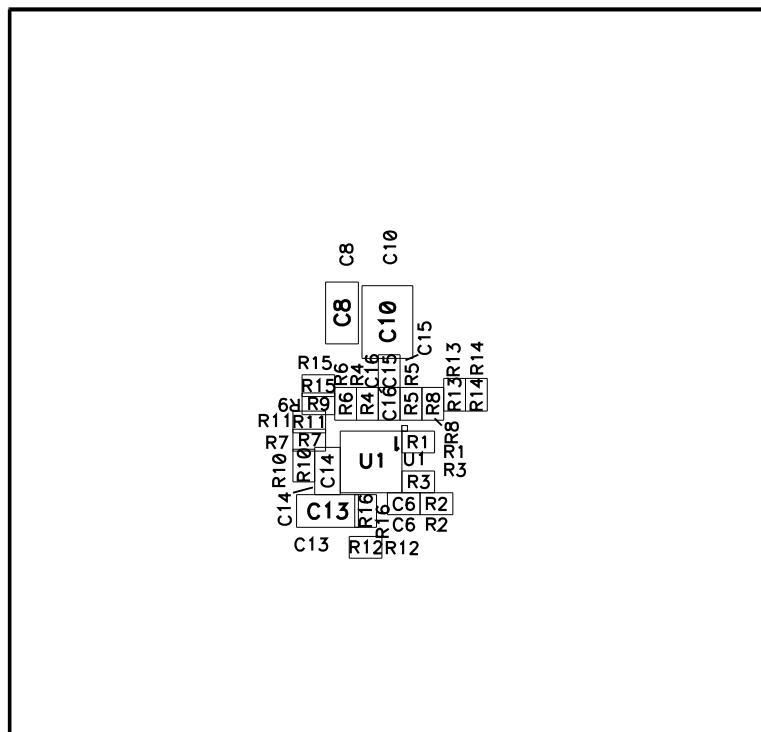


Figure 13. Bottom Layer Assembly Drawing (bottom view)

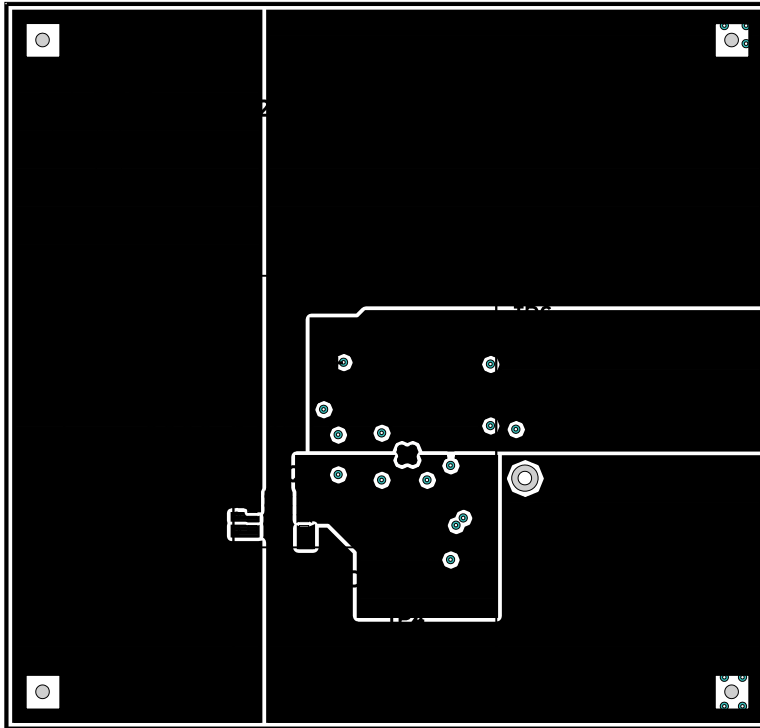


Figure 14. Top Copper

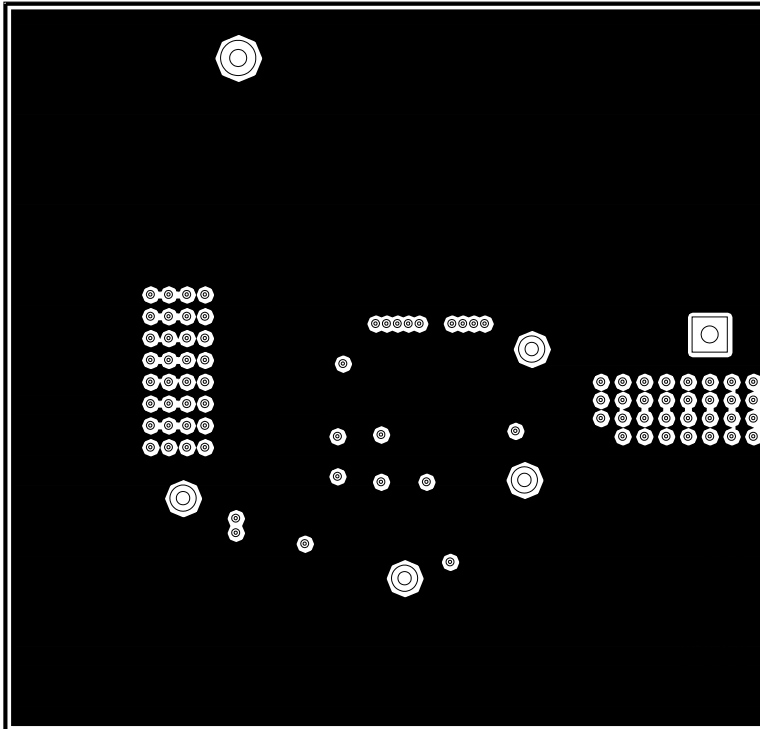
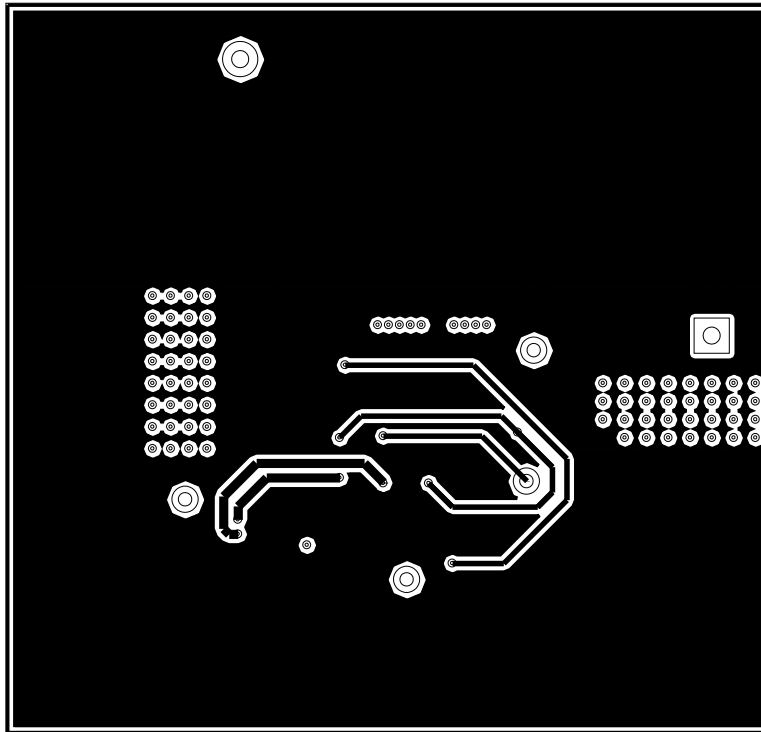
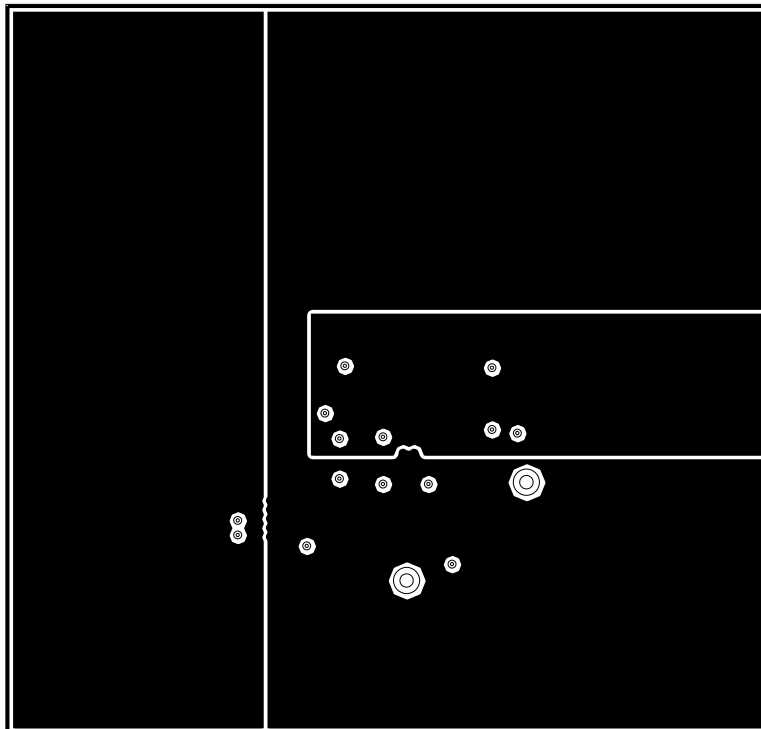


Figure 15. Layer 2



**Figure 16. Layer 3**



**Figure 17. Layer 4**

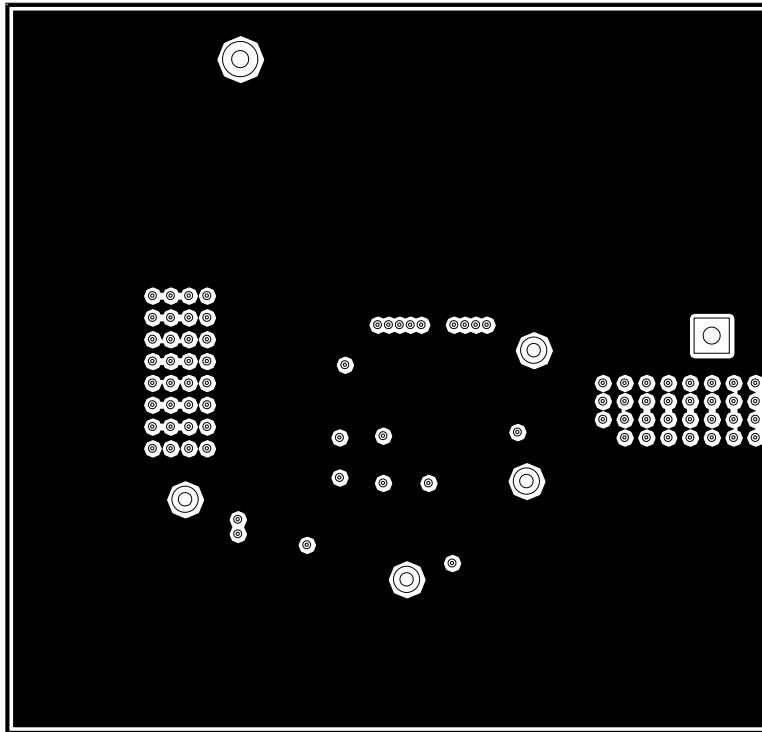


Figure 18. Layer 5

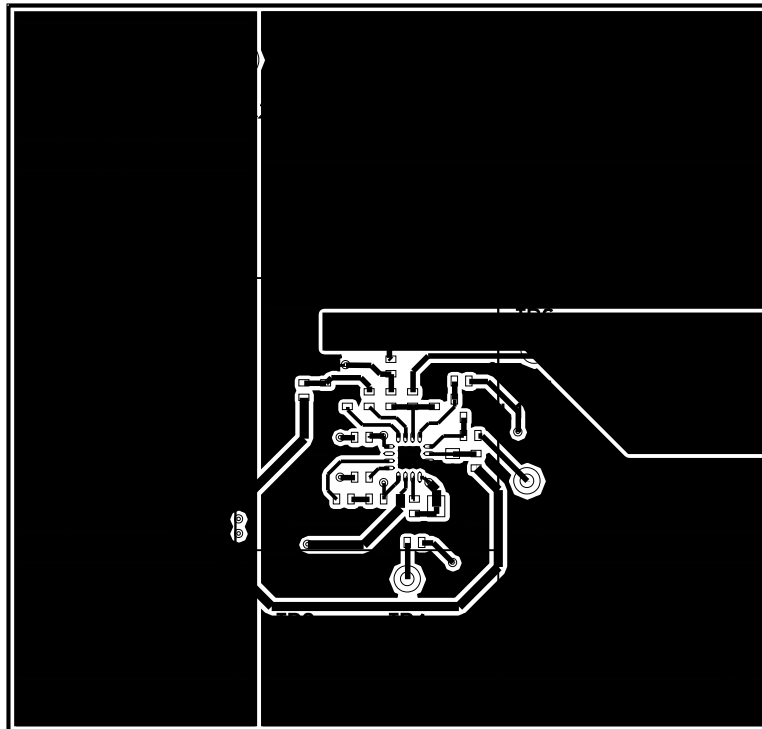


Figure 19. Bottom Layer

## 9 List of Materials

The EVM components list according to [Figure 1](#).

**Table 3. List of Materials**

| QTY | REF DES                           | DESCRIPTION  | MFR              | PART NUMBER   |
|-----|-----------------------------------|--|------------------|---------------|
| 1   | C1                                | Capacitor, ceramic, 25 V, X7R, 10%, 402  | Std              | Std           |
| 2   | C2, C14                           | Capacitor, ceramic, 25 V, X5R, 20%, 603  | Std              | Std           |
| 3   | C3, C4,<br>C5                     | Capacitor, ceramic, 25 V, X5R, 20%, 1210   | Std              | Std           |
| 2   | C6                                | Capacitor, ceramic, 16 V, X7R, 10%, 402  | Std              | Std           |
| 1   | C7                                | Capacitor, POSCAP, 330 $\mu$ F, 2.5 V, 0.009 $\Omega$ , 20%, Case B2805, 3528(B) | Sanyo            | 2R5TPE330MA9R |
| 2   | C8, C13                           | Capacitor, ceramic, 10 V, X5R, 20%,  | Std              | Std           |
| 0   | C9, C10,<br>C11, C12,<br>C15, C16 | Capacitor, ceramic, 6.3 V, X5R, 20%, 1210  | Std              | Std           |
| 1   | L1                                | Inductor, SMT, 24 A, 1.17 m $\Omega$ , 0.288 inch x 0.288 inch                   | Würth Elektronik | 7443320100    |
| 1   | Q1                                | MOSFET, Synchronous Buck NexFET Power Block, QFN-8 Power                         | TI               | CSD86330Q3D   |
| 3   | R1, R11,<br>R13                   | Resistor, chip, 1/16 W, 1%, 402  | Std              | Std           |
| 1   | R10                               | Resistor, chip, 1/16 W, 1%, 402  | Std              | Std           |
| 1   | R14                               | Resistor, chip, 1/16 W, 1%, 402  | Std              | Std           |
| 3   | R2, R3,<br>R16                    | Resistor, chip, 1/16 W, 1%, 402  | Std              | Std           |
| 2   | R4, R6                            | Resistor, chip, 1/16 W, 1%, 402  | Std              | Std           |
| 1   | R5                                | Resistor, chip, 1/16 W, 1%, 402  | Std              | Std           |
| 0   | R7, R9,<br>R12, R15               | Resistor, chip, 1/16 W, 1%, 402  | Std              | Std           |
| 1   | R8                                | Resistor, chip, 1/16 W, 1%, 402  | Std              | Std           |
| 1   | U1                                | Single Synchronous Step-Down Controller, QFN-16                                  | TI               | TPS53219RGT   |



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## EVM Warnings and Restrictions

It is important to operate this EVM within the input voltage range of 10 VDC to 14 VDC and the output voltage range of 0 ADC to 20ADC.

Exceeding the specified input range may cause unexpected operation and/or irreversible damage to the EVM. If there are questions concerning the input range, please contact a TI field representative prior to connecting the input power.

Applying loads outside of the specified output range may result in unintended operation and/or possible permanent damage to the EVM. Please consult the EVM User's Guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative.

During normal operation, some circuit components may have case temperatures greater than 100° C. The EVM is designed to operate properly with certain components above 100° C as long as the input and output ranges are maintained. These components include but are not limited to linear regulators, switching transistors, pass transistors, and current sense resistors. These types of devices can be identified using the EVM schematic located in the EVM User's Guide. When placing measurement probes near these devices during operation, please be aware that these devices may be very warm to the touch.

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| Power Mgmt                  | <a href="http://power.ti.com">power.ti.com</a>                     |
| Microcontrollers            | <a href="http://microcontroller.ti.com">microcontroller.ti.com</a> |
| RFID                        | <a href="http://www.ti-rfid.com">www.ti-rfid.com</a>               |
| RF/IF and ZigBee® Solutions | <a href="http://www.ti.com/lprf">www.ti.com/lprf</a>               |

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|                               |  |
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| Energy and Lighting           | <a href="http://www.ti.com/energy">www.ti.com/energy</a>                                 |
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| Medical                       | <a href="http://www.ti.com/medical">www.ti.com/medical</a>                               |
| Security                      | <a href="http://www.ti.com/security">www.ti.com/security</a>                             |
| Space, Avionics and Defense   | <a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a> |
| Transportation and Automotive | <a href="http://www.ti.com/automotive">www.ti.com/automotive</a>                         |
| Video and Imaging             | <a href="http://www.ti.com/video">www.ti.com/video</a>                                   |
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